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PATENT APPLICATION
(Attorney Docket No. 38219R2)

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

In re application of: Steven E. Koenck. **Examiner:** Hoa B. Trinh

Serial Number: 10/684,072 **Art Unit:** 2814

Filed: 10/13/2003

For: "Reduction of Electromagnetic Interference in Integrated Circuit Device Packages"

Commissioner for Patents
Alexandria, VA 22313

Declaration of Thomas Schuster

The undersigned, Thomas Schuster, hereby declares as follows:

(1) He is currently an employee of Intermec Technologies Corporation which has effective ownership of the above identified application.

(2) He has worked for Intermec and a predecessor Norand Corporation for twelve years, specializing in radio frequency communications systems and antenna design, and prior to that worked for seven years at Motorola Corporation specializing in radio frequency design and integrated circuit design. His present job title is Principal Engineer.

(3) He has reviewed the disclosure of the present Koenck application and of the Huang US Patent 5,138,431 (hereafter: "Huang").

(4) Huang notes at col. 1, line 67, to col. 2, line 5, that leadframes of copper have less desirable mechanical properties (e.g. are more easily bent and have a higher expansion coefficient) than leadframes of Alloy 42 which is a metallic alloy (42% nickel, 58% iron) with ferromagnetic properties. It is self-evident from the Huang disclosure that Alloy 42 is electrically conductive.

(4A) The purpose of FIGS. 6F and 6G at sheet 1 of the Huang drawings is clearly to add the mechanical properties of iron, cobalt or nickel, or an alloy of two or three of the ferromagnetic metals to leadframes of copper, so as to offset the

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disadvantages of copper leadframes as discussed at Huang col. 1, line 67, to col. 2, line 5; see Huang, col. 6, line 66, to col. 7, line 31.

(4B) Note the reference to ferromagnetic metals at col. 7, line 12, from which Declarant concludes that Huang is concerned with metallic ferromagnetic materials, while the subject Koenck disclosure is clearly directed to the use of non-metallic magnetic materials such as ferrites which have very high resistance.

(4C) Declarant has noted the following passage from the subject Koenck disclosure:

> [0023] In a preferred embodiment of the present invention a modeled plastic material 14 having desired electromagnetic properties to advantageously affect the signals to and from the integrated circuit 12 as the signals are routed through the lead frame conductors 16 of the device is utilized. A small amount of ferrite powder is preferably blended with the plastic material 14 to achieve the slightly lossy magnetic characteristic of the encapsulating plastic medium 14 surrounding the lead frame conductors 16. Ferrite is preferred because of its high resistivity and permeability. (Koenck US Publication 2004/0075175, Emphasis Supplied)

The Koenck disclosure above re blending a small amount of ferrite powder with plastic material 14 (and as reflected in Koenck claims 33 and 34) shows the strikingly different concepts of Koenck and Huang. The small amount of ferrite powder of Koenck clearly does not have any relation to the use of ferromagnetic metal in FIGS. 6F and 6G of Huang; the small amount of ferrite powder taught by Koenck would not itself prevent bending of copper leads (see Huang col. 1, line 67, to col. 2, line1).

CONCLUSIONS

(A) The material contemplated by the present Koenck disclosure (e.g. non-metallic ferrite material with high resistivity) is completely distinct from the ferromagnetic metals disclosed by Huang (see sections (4A) and (4B) above).

(B) The concepts of the present Koenck disclosure and Huang are strikingly different since Huang seeks a ferromagnetic metal as shown in FIGS. 6F and 6G of Huang with mechanical properties such as great tensile strength to provide

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rigidity to a copper leadframe, while Koenck teaches "blending a small amount of ferrite powder" (a non-metallic oxide material with characteristic high resistivity) in the encapsulating plastic medium 14 to achieve a slightly lossy magnetic characteristic (see section (4C) above). Huang, of course, requires the support of the copper leadframe by the metallic ferromagnetic material **prior to encapsulation**, while the leadframe is being connected by means of bonding wires 32, to die 24, FIG. 4.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Thomas Schuster

Thomas Schuster

Date: May 15, 2006